

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Seigi AOYAMA et al.

Application S/N 09/892,630

Filed: June 28, 2001



Art Unit: 2827

Examiner: T. Dinh

For: LEAD-FREE SOLDER, AND CONNECTION LEAD AND ELECTRICAL
COMPONENT USING SAID LEAD-FREE SOLDER

AMENDMENT

Honorable Assistant Commissioner
for Patents
Washington, DC 20231

Sir:

In response to the Final Official Action dated November 19, 2002, the time for response to which is extended by one (1) month up to and including March 19, 2003, please amend the above referenced application as follows.

IN THE CLAIMS

Please cancel claims 3, 6 and 8-13.

Please amend claim 2 to read as follows (see also Appendix of Claim Amendments):

2. (Twice Amended) A lead-free solder comprising an alloy composition containing 2.0 to 5.0% by mass of silver, 0.01 to 2.0% by mass of copper, and 0.002 to 0.015% by mass of phosphorus with the balance consisting of tin.

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